Almost every great advancement in technology can be attributed to a breakthrough in materials science. Since the company’s founding in 1934, Indium Corporation has been driven by its curiosity to look at materials from a different perspective—transforming the ordinary into the unexpected.
It is our culture—
The Indium Way—that continually supports our commitment to changing the world through materials science.

The **IndiumWay**.

respect. appreciation. achievement.

**Greg Evans**
Chief Executive Officer
OUR GOAL
YOUR SUCCESS
Increase our customers’ productivity and profitability through premium design, application, and service of advanced materials.

OUR BASIS
FOR SUCCESS
- Excellent product quality and performance
- Technical and customer service
- Cutting-edge material research and development
- Extensive product range
- Lowest cost of ownership

Ross Berntson
President and Chief Operating Officer (COO)
Indium Corporation is founded at 805 Watson Place, Utica, NY, USA.

Indium Corporation begins the development of solder pastes—the first step in a long history of developing high-reliability solder pastes that address industry challenges, comply with regulation updates, and surpass industry testing standards.

Indium Corporation develops the first ultra-low residue no-clean flip-chip fluxes for the semiconductor industry—the NC-26 series.

Indium Corporation develops and introduces InFORMS® solder preforms, which solve substrate tilt by providing the most uniform bondline control—offering a >2X increase in reliability.

Indium Corporation earns ISO/IATF 16949 management system certificates for all of its solder paste and preform manufacturing facilities in Clinton and Utica, NY, USA; Singapore; Milton Keynes, UK; and China—as well as the company’s headquarters—reaffirming Indium Corporation’s materials are produced with the utmost quality to ensure the reliability of customers’ finished goods.

Indium Corporation launches innovative low-temperature high-reliability alloy Durafuse™ LT technology.
OUR COMMITMENT TO QUALITY

• Provide quality products that meet or exceed customer needs, expectations, and requirements
• Create an organizational culture that focuses on meeting requirements and continuous improvement
• Have products that are compliant with relevant laws and regulations
• Focus on defect prevention
• Respond to input from external and internal customers
• Identify and provide necessary resources

Mike McNamara
Corporate Quality Director

CODE OF CONDUCT

Indium Corporation’s professional commitment to our customers, our peers, our organization, and ourselves includes a defined Code of Conduct that covers:
• Ethics
• Workforce
• Health and Safety
• Environment
• Management Systems

INDIUM PEOPLE CARE

We’re also active in our local communities through volunteering, sponsorships, and mentoring.
Indium Corporation is a premier materials refiner, smelter, manufacturer, and supplier to the global electronics, semiconductor, thin-film, and thermal management markets. We develop, manufacture, and market solders; electronics assembly and packaging materials; pure indium, gallium, germanium, and tin; as well as alloys and inorganic compounds. We offer a closed-loop reclaim system for these metals.

Indium Corporation’s scientists, application engineers, and technical support engineers work closely with our customers to develop custom solutions to their technical problems and optimize their processes to:

- Increase yields
- Increase revenues
- Improve customer satisfaction
- Reduce defects
- Deliver high value
- Improve customer satisfaction and return on investment

INNOVATIVE RESEARCH LABS

Advanced Materials and Process Development Labs:
To fully characterize materials and processes in leading-edge technology applications.

Thermal Lab:
To analyze the thermal resistance and conductivity properties of thermal interface materials to help determine the optimal applications.

Research and Development Labs:
To advance materials science for the creation of new and unique products.

Tech Hubs:
To provide for the effective development of electronics assembly expertise and customer service.
As a key manufacturer and supplier to the global markets, Indium Corporation® is committed to environmental responsibility, which is vital to the sustainability of our business, our products, our brand, and our place in the community. Our scientists and engineers work closely with our customers and partners to apply materials science-based innovations in the electronics industry—from increasing a product’s lifespan to our state-of-the-art electrolytic recycling processes. As your strategic partner, Indium Corporation® works together with you to reduce the environmental impact of electronics manufacturing. Here are some ways we are helping minimize the environmental footprint within electronics assembly and packaging.

- REACH-compliant materials
  - Majority of our solder fluxes
- Lead-free and Halogen/Halide-free products
  - Lead-free high-temperature replacement materials
- Low-temperature processes and materials
  - Reducing assembly energy consumption and carbon footprint in the electronics assembly process
- Recycled tin materials
- Supplier of Reclaim and Recycle services
  - Dross reclaim
  - Indium-containing materials, such as InP, ITO, and used targets

As a responsible member of our communities, Indium Corporation® is committed to developing conservation strategies and adopting eco-friendly solutions to build a more sustainable future.
MARKETS SERVED

- Auto/EV
- 5G Infrastructure
- Mobile
- IoT/Al
- Laser/Fiber Optics
- LED
- Photovoltaic
- Metal Refining & Reclaim
- Battery
- RF/Microwave
- Thermal Management
- Downhole

www.indium.com
1,200+ **EMPLOYEES**

15 **FACILITIES**

85+ years **OF CONSISTENT GROWTH**

**Quality Certifications/Compliance**
- IATF 16949:2016
- ISO 14001:2004
- ISO 9001:2015
- REACH
- RoHS
- IMDS
Our materials enable the manufacture of strong, reliable products that endure the inevitable physical shocks and thermal stresses associated with electronics devices in applications from the IoT mobile devices—to next-generation, low-energy servers—to automobile electronics.

We provide solutions for:

- Heterogeneous integration/system-in-package
- 2.5D and 3D devices
- Chip-on-wafer and interposer
- Flip-chip on substrate and leadframe
- Ball grid array (BGA) and wafer-/panel-level packages
- Mini/microLED devices
- Power/analog discretes and small modules (<600V)
- High-voltage power modules (>600V)
- Specialty small component assemblies
The electronics industry continues to rapidly evolve to increasingly smaller, more sophisticated devices with increased power. Indium Corporation is known as the global leader in R&D, product performance, technical service, and process optimization. We are also partners with most of the world’s leading electronics manufacturers.

Our high-reliability solutions include:

- Solder pastes
- Flux-cored wires
- Wave solder fluxes
- Bar solder
- Tacky fluxes
- Solder preforms
- PoP fluxes and pastes
- And more

www.indium.com/solders

Chris Bastecki
Director of Electronics Assembly Materials

AVOID:
- DENDRITIC GROWTH
- VOIDING
- CRACKING
- SOLDER BEADING
- NON-WET OPENS
- INSUFFICIENT SOLDER DEPOSITS
- HEAD-IN-PILLOW
Our precision solder preforms are available in a wide range of problem-solving alloys, with exacting tolerances and creative packaging to provide the basis for our customers to create next-generation technologies.

We provide solutions for:
- Reflow of temperature-sensitive components
- Voiding
- Solder starvation
- CTE mismatch
- Mechanical and electrical reliability
- Bondline planarity

Jon Major
Associate Director
ESM Product Management

www.indium.com/preforms
Indium Corporation’s high-performance metal-based thermal interface materials (TIMs) provide industry-leading thermal performance and overall product life. Our innovations have expanded upon the high thermal conductivity of metal by creating unique patterning options and hybrid solutions that eliminate the interfacial resistance challenges normally associated with metal TIMs.

Our research has created critical thermal management products, including:

- Heat-Spring®
- Solder TIMs
- m2TIM™
- Liquid Metal Paste
- Liquid Metal

www.indium.com/TIMs
METALS & COMPOUNDS

From the mine to product packaging, we set the standard for the processing of indium, germanium, gallium, and tin. Quality is assured because we control the process from the very first step.

Indium Corporation is the world’s premier supplier of:

- Commercial-grade and ultra-high-purity indium metal
- Indium compounds
- Germanium metal and compounds
- Gallium metal and compounds
- Tin metal and alloys
- Fusible alloys, including Field’s metal
- Targets
- Reclaim services

Robert Ploessl
Manager of Marketing and Technology Assessment and Product Manager, Metals and Compounds

www.indium.com/metals
www.indium.com/compounds
When even 10ppm of contamination can cause process and application failures, quality counts. **We cast our own alloys, which enables us to closely control the process from start to finish and ensure purity.** This is why we are a leading innovator of joining and bonding materials for medical, aerospace, optoelectronics, and automotive applications.

**High-Temperature Gold Solder Materials Deliver:**

- Highest tensile strength of any solder
- Compatible with subsequent reflow processes
- Pb-free and RoHS compliant
- Superior thermal conductivity
- Resistance to corrosion
- Superior thermal fatigue resistance
- Good joint strength
- Excellent wetting properties
- Resistance to oxidation
Our Goal
Increase our customers’ productivity and profitability through the design, application, and service of advanced materials.

Corporate Quality Policy
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Materials Supplier
• SMT and SiP solder pastes and fluxes
• Power semiconductor die-attach
• Semiconductor fluxes
• Thermal interface materials
• Engineered solders
• Inorganic compounds
• High-temperature solder materials

Global Technical Support and Facilities Worldwide

Contact our engineers: askus@indium.com
Learn more: www.indium.com

From One Engineer To Another
All of Indium Corporation’s solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

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